

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
K. OKAJIMA, et al.

Serial No.: To Be Assigned

Art Unit: To Be Assigned

Filed: Concurrently herewith

Examiner: To Be Assigned

For: Method For Forming Solder-Resist Film

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 and 1.98

Cmmisioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

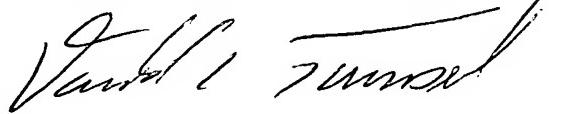
22241 U.S. PTO
10/630858
07/31/03


Sir:

In compliance with the dictates of 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicants hereby submit an Information Disclosure Statement.

It is respectfully requested that the Examiner consider this reference and indicate such consideration by enclosing an appropriately initialed copy of the enclosed form PTO-1449 with the next communication from the Patent Office.

Respectfully submitted,



Donald E. Townsend
Reg. No. 22,069

Date: July 31, 2003

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*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.